

IPC J-STD-006C
Amendment 1
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JOINT INDUSTRY STANDARD

Requirements for
Electronic Grade Solder
Alloys and Fluxed and
Non-Fluxed Solid
Solders for Electronic
Soldering Applications

Amendment 1



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In May 1995 the IPC's Technical Activities Executive Committee (TAEC) adopted Principles of Standardization as a guiding principle of IPC's standardization efforts.

Standards Should:

- Show relationship to Design for Manufacturability (DFM) and Design for the Environment (DFE)
- Minimize time to market
- Contain simple (simplified) language
- Just include spec information
- Focus on end product performance
- Include a feedback system on use and problems for future improvement

Standards Should Not:

- Inhibit innovation
- Increase time-to-market
- Keep people out
- Increase cycle time
- Tell you how to make something
- Contain anything that cannot be defended with data

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IPC J-STD-006C-AM1

Requirements for Electronic Grade Solder Alloys and Fluxed and Non-Fluxed Solid Solders for Electronic Soldering Applications

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Developed by the Solder Alloy Task Group (5-24c) of the Assembly
and Joining Committee (5-20) of IPC

Users of this standard are encouraged to participate in the
development of future revisions.

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Acknowledgment

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